ABSTRACT

A semiconductor device is provided which is capable of improving the productivity, the reliably, and the shielding of exposed parts such as leads or others and preventing chipping. The semiconductor device comprises a semiconductor chip 10, an insulating member 20 adhered onto an electrode terminal-forming surface 10a of a semiconductor chip 10, a circuit pattern 30 having at one end a land 32 to be connected to an external connection terminal, provided on the insulating member 20, and at the other end a lead 34 to be connected to an electrode terminal 12, a cover member 52 having an outer size larger than that of the semiconductor chip 10 to cover not only the electrode terminal-forming surface 10a and the lead 34 but also the outer edge of the semiconductor chip 10, and a resin shield 50 formed by filling a resinous sealant into a gap between the electrode terminal-forming surface 10a and the cover member 52 and curing the same, which shields the electrode terminal-forming surface 10a, the lead 34 and a side surface of the semiconductor chip 10.